

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Heung Jae Chun	10/04/2011
Su Jung You	10/04/2011
Ki Dong Yoo	10/10/2011
Kyu Nam Park	10/04/2011
Gue Tae Chae	10/04/2011
Seok Whan Moon	10/11/2011
Han Joon Kim	10/11/2011
Jung Hee Wee	10/10/2011

**RECEIVING PARTY DATA**

<b>Name:</b>	Catholic University Industry Academic Cooperation Foundation
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<b>City:</b>	Seoul
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>Postal Code:</b>	137-040

**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	13266677

**CORRESPONDENCE DATA**

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**PATENT**

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ASSIGNMENT

WHEREAS, we

Inventor 1, CHUN, HEUNG JAE residing at 1433, Hwanghak-dong, Jung-gu, Seoul, 100-440, The Republic of Korea,

Inventor 2, YOU, SU JUNG residing at Jugong Apt. 306-403, Dunchon 1-dong, Gangdong-gu, Seoul, 134-773, The Republic of Korea,

Inventor 3, YOO, KI DONG residing at 136, Daesin-dong, Seodaemun-gu, Seoul, 120-160, The Republic of Korea,

Inventor 4, PARK, KYU NAM residing at Character Greenville Apt. 1202, Sindaebang-dong, Dongjak-gu, Seoul, 156-010, The Republic of Korea,

Inventor 5, CHAE, GUE TAE residing at Samho Apt. 3-201, Seocho 4-dong, Seocho-gu, Seoul, 137-786, The Republic of Korea,

Inventor 6, MOON, SEOK WHAN residing at Kukdong Apt. 112-801, Hyeonjeo-dong, Seodaemun-gu, Seoul, 120-796, The Republic of Korea,

Inventor 7, KIM, HAN JOON residing at Gaepo Hanshin Apt. 4-714, Dogok 2-dong, Gangnam-gu, Seoul, 135-855, The Republic of Korea, and

Inventor 8, WEE, JUNG HEE residing at Gangsan Sweetvill 201, 386-4, Yangjae 2-dong, Seocho-gu, Seoul, 137-899, The Republic of Korea,

have invented new and useful improvements in **INVENTION TITLE, BIODEGRADABLE SUTURE TYPE CELL DELIVERY SYSTEM FOR IMPROVING STEM CELL ENGRAFTMENT RATE** and have executed an application for United States Letters Patent, and

WHEREAS, CATHOLIC UNIVERSITY INDUSTRY ACADEMIC COOPERATION FOUNDATION organized and existing under the laws of The Republic of Korea, having a place of business at Catholic University Industry Academic Cooperation Foundation, 505, Banpo-dong, Seocho-gu, Seoul, 137-040, The Republic of Korea, (Hereinafter "Assignee") is desirous of acquiring the entire right, title, and interest in and to said invention, said application, and in to and under all Letters Patent of the United States and

foreign countries that may be granted therefor;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration to me in hand and paid by said Assignee the receipt of which is hereby acknowledged, we, said Inventor 1 and Inventor 2 have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over to and unto said Assignee, its successors and assigns, for, within and throughout the United States and the territories thereof, and all foreign countries, the entire right, title and interest in and to said invention, and in, to and under said application, and all Letters Patent of the United States and foreign countries that may be granted for said invention and improvements, including divisions, reissues, subdivisions, continuations and prolongations of such applications and Letters Patent, to have and to hold for the sole and exclusive use and benefit of said Assignee, its successors and assigns, to the full end of the term or terms for which any and all of said Letters Patent for said invention may issue, and further, including the right to Assignee to file in its name applications for Letters Patent to said improvements in any country or countries foreign to the United States including the full right to claim for any such applications the priority benefits of the International Convention for the Protection of Industrial Property and other priority conferring treaties, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof.

We do hereby covenant and agree, for ourselves, heirs and legal representatives, that we will assist said Assignee in the prosecution of the application herein identified; in the making and prosecution of any other applications for Letters Patent that said Assignee may elect to make covering the invention herein identified, as hereinbefore set forth; in vesting in said Assignee, like exclusive title in and to all such other applications and Letters Patent; and in the prosecution of any interference which may arise involving said invention, or any application or Letters Patent herein contemplated; and that we will execute and deliver to said Assignee, any and all additional papers that may be requested by said Assignee, to fully carry out the terms of this assignment.

And we do hereby authorize and request the Commissioner of Patents to issue all Letters Patent of the United States that may be granted pursuant to application aforesaid, or for said invention, to said Assignee, its successors and assigns in accordance with this assignment.

And we hereby covenant that we have full right to convey the entire interest herein assigned, and that we have not executed and will not execute any agreement in conflict herewith.

4th / Oct. / 2011  
Date

CHUN, HEUNG JAE  
INVENTOR 1

*Heung Jae Chun*

4th / Oct / 2011  
Date

YOU, SU JUNG  
INVENTOR 2

*Su Jung You*

10th / Oct / 2011  
Date

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INVENTOR 3

*Ki Dong Yoo*

4th / Oct. / 2011  
Date

PARK, KYU NAM  
INVENTOR 4

*Kyu Nam Park*

Oct 4 2011  
Date

CHAE, GUE TAE  
INVENTOR 5

*Gue Tae Chae*

Oct 11 2011  
Date

MOON, SEOK WHAN  
INVENTOR 6

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11th / Oct / 2011  
Date

KIM, HAN JOON  
INVENTOR 7

*Han Joon Kim*

10th / Oct / 2011  
Date

WEE, JUNG HEE  
INVENTOR 8

*Jung Hee Wee*